16 Vcc

15 MR

14 CP

13 CE

12 TC

11 9

10 4

9 8

F PACKAGE (TOP VIEW)

5

1 12

2

7 6

3 17

GND 8

0 🛚 з

6 **[**5

Π4

- 4.5-V to 5.5-V Operation
- Fully Static Operation
- Buffered Inputs
- Common Reset
- Positive-Edge Clocking
- Balanced Propagation Delay and Transition Times
- Direct LSTTL Input Logic Compatibility
  V<sub>IL</sub> = 0.8 V Maximum; V<sub>IH</sub> = 2 V Minimum
- CMOS Input Compatibility – I<sub>I</sub>  $\leq$  1  $\mu$ A at V<sub>OL</sub>, V<sub>OH</sub>
- Packaged in Ceramic (F) DIP Packages and Also Available in Chip Form (H)

descri	ption

The CD54HCT4017 is a high-speed silicon-gate CMOS 5-stage Johnson counter with ten decoded outputs. Each decoded output normally is low and sequentially goes high on the low-to-high transition of the clock (CP) input. Each output stays high for one clock period of the ten-clock-period cycle. The terminal count (TC) output transitions low to high after output ten (9) goes low, and can be used in conjunction with the clock enable ( $\overline{CE}$ ) input to cascade several stages.  $\overline{CE}$  disables counting when in the high state. The master reset (MR) input, when taken high, sets all the decoded outputs, except 0, to low.

The CD54HCT4017 is characterized for operation over the full military temperature range of -55°C to 125°C.

**FUNCTION TABLE** 

	INPUTS							
СР	CE	MR	OUTPUT STATE†					
L	Х	L	No change					
Х	Н	L	No change					
х	Х	Н	0 = H 1–9 = L					
$\uparrow$	L	L	Increments counter					
$\downarrow$	Х	L	No change					
Х	$\uparrow$	L	No change					
Н	$\downarrow$	L	Increments counter					
+ 16		Le sub-survey	LA TO I					

<sup>†</sup> If n < 5, TC = H; otherwise, TC = L.



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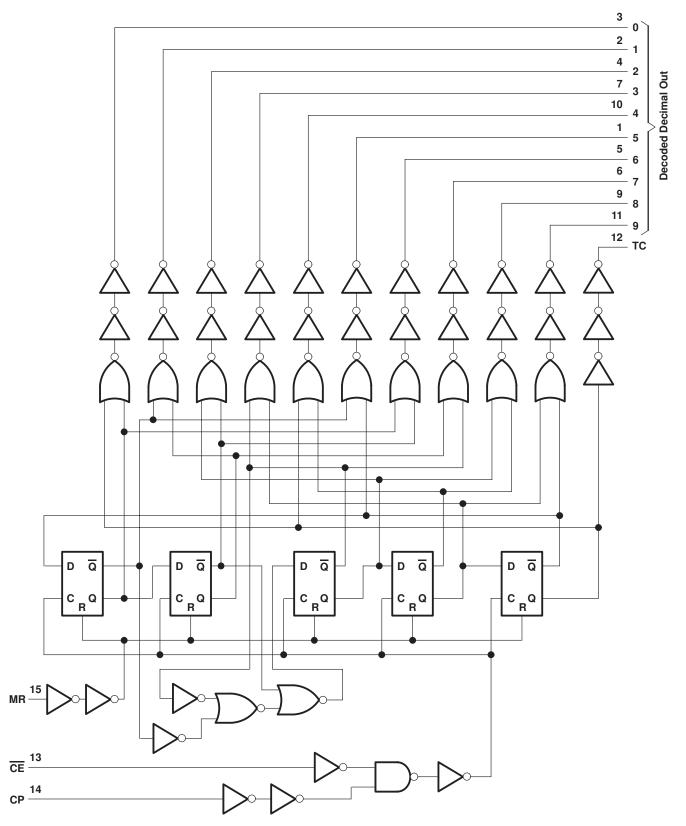
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### logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input clamp current, $I_{IK}$ (V <sub>I</sub> < 0 V or V <sub>I</sub> > V <sub>CC</sub> )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ V or $V_O > V_{CC}$ )	±20 mA
Continuous output current, each output pin, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±25 mA
V <sub>CC</sub> or ground current, I <sub>CC</sub>	
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2		V
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.8	V
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	VCC	V
		$V_{CC} = 2 V$	0	1000	
tt	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V	0	500	ns
	V <sub>CC</sub> = 6 V		0	400	
ТА	Operating free-air temperature		-55	125	°C

NOTE 1: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to TI application report Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Vee	T <sub>A</sub> = 25°C				МАХ	UNIT
F7		TEST C	TEST CONDITIONS V <sub>CC</sub>		MIN TYP MA		MAX			UNIT
Vou	CMOS loads	$V_I = V_{IH} \text{ or } V_{IL},$	I <sub>O</sub> = -0.02 mA	4.5 V	4.4			4.4		V
VOH	TTL loads	$V_I = V_{IH} \text{ or } V_{IL},$	I <sub>O</sub> = -4 mA	4.5 V	3.98			3.7		v
Val	CMOS loads	$V_I = V_{IH} \text{ or } V_{IL},$	I <sub>O</sub> = 0.02 mA	4.5 V			0.1		0.1	V
VOL	TTL loads	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{O} = 4 \text{ mA}$	4.5 V			0.26		0.4	v
Ц		VI = ACC to 0		5.5 V			±100		±1000	nA
ICC		AI = ACC  or  0		5.5 V			8		160	μA
∆lcc†		$V_{I} = V_{CC}$ to 2.1 V,	$I_{O} = 0$	4.5 to 5.5 V		100	360		490	μA
Ci							10		10	pF

<sup>†</sup> For dual-supply systems, theoretical worst case (V<sub>I</sub> = 2.4 V, V<sub>CC</sub> = 5.5 V) specification is 1.8 mA.

#### **INPUT LOADING**

INPUT	UNIT LOAD				
CP	0.15				
CE	0.25				
MR 0.3					

Unit load is  $\Delta I_{CC}$  limit, e.g., 360  $\mu$ A MAX at T<sub>A</sub> = 25°C.

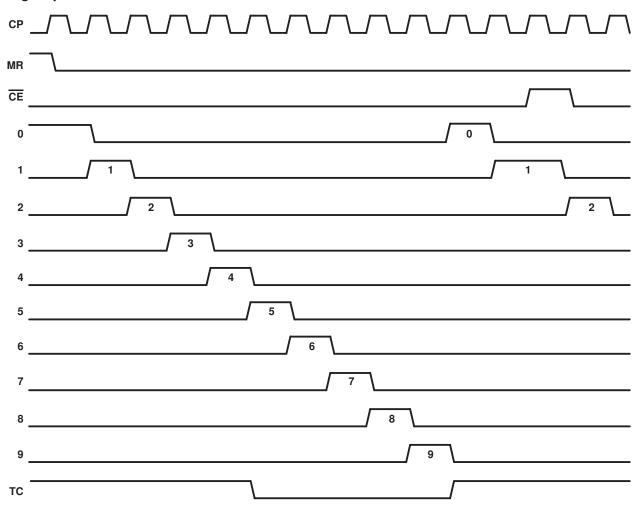
### timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER				T <sub>A</sub> = 25°C		MIN MAX	
					MAX		WIAA	UNIT
fclock	Maximum clock frequency		4.5 V		25		17	MHz
+	Pulse duration	СР	4.5 V		16		24	20
tw		MR	4.5 V		16		24	ns
t <sub>su</sub>	Setup time, CE to CP		4.5 V	15		22		ns
t <sub>h</sub>	Hold time, CE to CP		4.5 V	0		0		ns
t <sub>rem</sub>	Removal time, MR		4.5 V	5		5		ns



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timing requirements





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# switching characteristics, $C_L$ = 50 pF, $T_A$ = 25°C (see Figures 1 and 2)

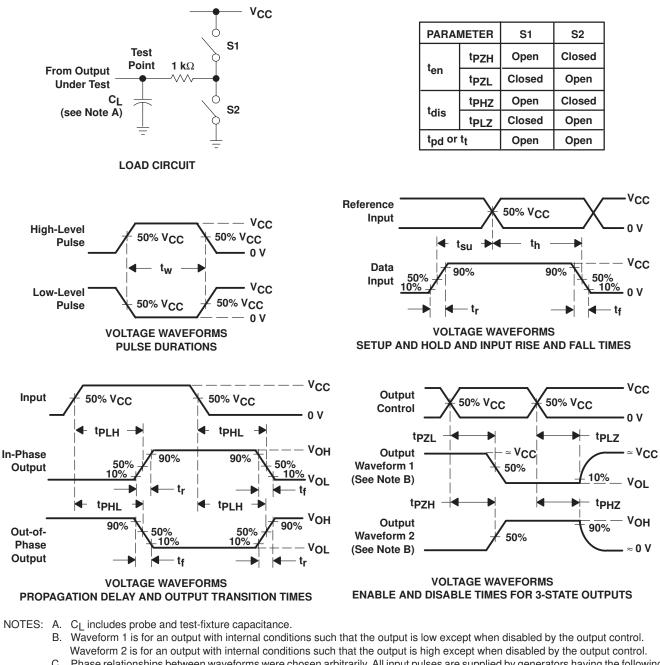
PARAMETER	FROM (INPUT)			T <sub>A</sub> = 2	25°C	T <sub>A</sub> = - TO 12		UNIT
	(INPOT)	(001401)	Vcc	MIN	MAX	MIN	MAX	
fmax			4.5 V	25		17		MHz
<sup>t</sup> PLH	CP	Any output	4.5 V		46		69	ns
<sup>t</sup> PHL	0F	TC	4.5 V		46		69	115
<sup>t</sup> PLH	CE	Any output	4.5 V		50		75	20
<sup>t</sup> PHL	CE	TC	4.5 V		50		75	ns
<sup>t</sup> PLH	MR	Any output	4.5 V		46		69	20
<sup>t</sup> PHL	IVIN	TC	4.5 V		46		69	ns
<sup>t</sup> THL		Any output	4.5 V		15		22	ns
<sup>t</sup> TLH		TC	4.5 V		15		22	115

### operating characteristics

	PARAMETER		TYP	UNIT
Cpd	Power dissipation capacitance	No load	39	pF



### PARAMETER MEASUREMENT INFORMATION

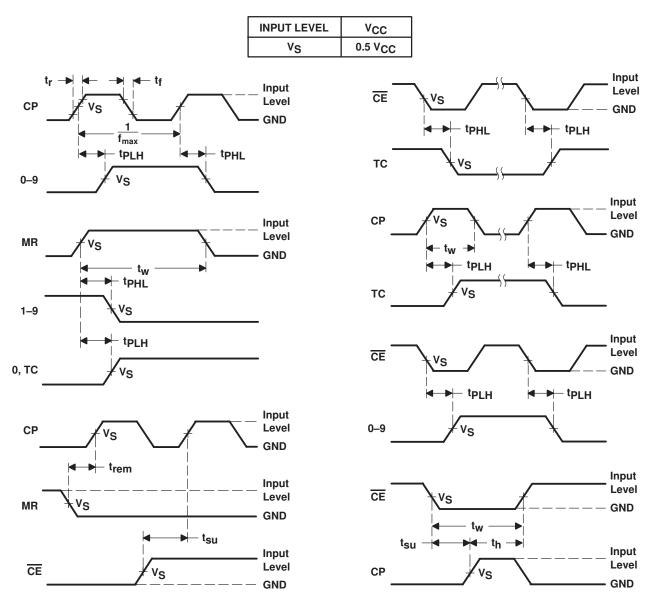


- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. tPZL and tPZH are the same as ten.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms



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#### PARAMETER MEASUREMENT INFORMATION





### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54HCT4017F3A	OBSOLETE	CDIP	J	16	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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